

IN THE CLAIMS:

Please amend claims 1,2, 4, 12, 13, 15, 17, 20 and 28 as follows:

1. (Currently amended) An active smart antenna system comprising:

an antenna for receiving a signal;

a low noise amplifier for amplifying a signal received through the antenna so as to minimize a noise generation; and

a phase shifter for controlling a phase of the amplified signal,

wherein the antenna, the low noise amplifier, and the phase shifter are formed on one high resistance substrate that is essentially non-conductive.
2. (Currently amended) The active smart antenna system of claim 1, wherein the high resistance substrate is one selected ~~from~~ among a high resistance silicon substrate, a high resistance ceramic substrate, and a printed circuit board (PCB).
3. (Original) The active smart antenna system of claim 2, wherein the high resistance substrate is a substrate of two surfaces having signal electrodes for connecting upper and lower surfaces thereof.
4. (Currently amended) The active smart antenna system of claim 2, wherein the antenna is one ~~between~~ of a patch antenna and a slot antenna.
5. (Original) The active smart antenna system of claim 2, wherein the phase shifter is constituted with signal electrodes, ground electrodes, inductors respectively formed of the same conductive material, and an electron switch and a capacitor connected to the signal electrodes.

6. (Original) The active smart antenna system of claim 5, wherein the inductor is formed as a strip line structure or a spiral structure by a micro electro mechanical system (MEMS) technique.

7. (Original) The active smart antenna system of claim 5, wherein the electron switch is formed as a bare chip form that is connected to the signal electrodes by a bonding wire.

8. (Original) The active smart antenna system of claim 7, wherein the electron switch further includes a polymeric protection material.

9. (Original) The active smart antenna system of claim 5, wherein the electron switch is formed at an etched part of the high resistance substrate after partially etching the high resistance substrate.

10. (Original) The active smart antenna system of claim 5, wherein the electron switch is formed as a bare chip form connected to the signal electrodes by a flip chip bonding technique.

11. (Original) The active smart antenna system of claim 10, wherein the electron switch further includes a polymeric protection material.

12. (Currently amended) The active smart antenna system of claim 23, wherein the low noise amplifier is formed as a bare chip form connected to the signal electrodes by a bonding wire.

13. (Currently amended) The active smart antenna system of claim 23, wherein the low noise amplifier is formed as a bare chip form connected to the signal electrodes by a flip chip bonding technique.

14. (Previously presented) The active smart antenna system of claim 1, wherein the high resistance substrate is a Low temperature co-fired ceramic (LTCC) PCB.

15. (Currently amended) The active smart antenna system of claim 14, wherein the phase shifter is constituted with signal electrodes, ground electrodes, inductors respectively formed of the same conductive material, and an electron switch and a capacitor connected to the signal electrodes.

16. (Original) The active smart antenna system of claim 15, wherein the inductor is stacked inside the high resistance substrate.

17. (Currently amended) A method for fabricating an active smart antenna system, wherein an antenna for receiving a signal, a low noise amplifier for amplifying a signal received through the antenna so as to minimize a noise generation, and a phase shifter for controlling a phase of the amplified signal are formed on one high resistance substrate that is essentially non-conductive.

18. (Original) The method of claim 17, wherein the high resistance substrate is one selected among a high resistance silicon substrate, a high resistance ceramic substrate, and a printed circuit board (PCB).

19. (Original) The method of claim 18, wherein the high resistance substrate is a substrate of two surfaces having signal electrodes for connecting upper and lower surfaces thereof.

20. (Currently amended) The method of claim 18 comprising the steps of:
uniformly forming a conductive layer on one high resistance substrate;
patterning the conductive layer and thereby forming signal electrodes, ground
electrodes, and inductors; and

respectively forming an electron switch ~~and a capacitor connected to the signal
electrodes and the ground electrodes~~connected to the signal electrodes on the ground
electrodes and forming a capacitor connected to the signal electrodes on the signal
electrodes.

21. (Original) The method of claim 20, wherein the electron switch is formed
as a bare chip form connected to the signal electrodes by a bonding wire.

22. (Original) The method of claim 21, further comprising a step for forming a
polymeric protection material for protecting the electron switch.

23. (Original) The method of claim 20, wherein the electron switch is formed
as a bare chip form connected to the signal electrodes by a flip chip bonding technique.

24. (Original) The method of claim 23, further comprising a step for forming a
polymeric protection material for protecting the electron switch.

25. (Original) The method of claim 20, wherein the electron switch is formed
at an etched part of the high resistance substrate after partially etching the high
resistance substrate.

26. (Original) The method of claim 25, further comprising a step for forming a
polymeric protection material for protecting the electron switch.

27. (Original) The method of claim 20, further comprising a step for forming an antenna by patterning the conductive layer.

28. (Currently amended) The method of claim 27, wherein the antenna is one ~~between~~of a patch antenna and a slot antenna.

29. (Original) The method of claim 20, further comprising a step for forming a low noise amplifier connected to the signal electrodes.